

(12) **United States Patent**
Josell et al.

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(54) **SUPERCONFORMAL FILLING
COMPOSITION AND
SUPERCONFORMALLY FILLING A
RECESSED FEATURE OF AN ARTICLE**

(52) **U.S. Cl.**
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(Continued)

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(58) **Field of Classification Search**
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C25D 7/00; *C25D 7/123*; *C25D 5/02*;
(Continued)

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(*) Notice: Subject to any disclaimer, the term of this
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(57) **ABSTRACT**

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Superconformally filling a recessed feature includes: contacting the recessed feature with superconformal filling composition that includes: $\text{Au}(\text{SO}_3)_2^{3-}$ anions; SO_3^{2-} anions; and Bi^{3+} cations; convectively transporting $\text{Au}(\text{SO}_3)_2^{3-}$ and Bi^{3+} to the bottom member of the recessed feature; subjecting the recessed feature to an electrical current to superconformally deposit gold from the $\text{Au}(\text{SO}_3)_2^{3-}$ on the bottom member relative to the sidewall and the field, the electrical current providing a cathodic voltage; and increasing the electrical current subjected to the field and the recessed feature to maintain the cathodic voltage between -0.85 V and -1.00 V relative to the SSE during superconformally depositing gold on the substrate to superconformally fill the recessed feature of the article with gold as a superconformal filling of gold, the superconformal filling being void-free and seam-free.

(65) **Prior Publication Data**
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(Continued)

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27 Claims, 56 Drawing Sheets

